

REGULATORY COMPLIANCE











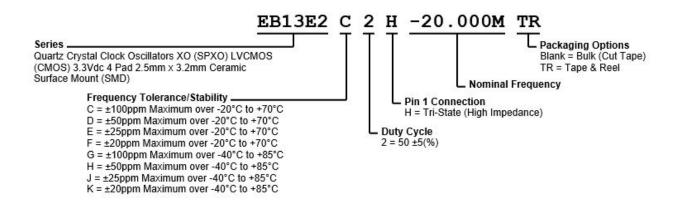
ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 2.5mm x 3.2mm Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICAT	TIONS
Nominal Frequency	1.024MHz to 66.6666MHz
Frequency Tolerance/Stability	Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration
	±100ppm Maximum over -20°C to +70°C
	±50ppm Maximum over -20°C to +70°C
	±25ppm Maximum over -20°C to +70°C
	±20ppm Maximum over -20°C to +70°C
	±100ppm Maximum over -40°C to +85°C
	±50ppm Maximum over -40°C to +85°C
	±25ppm Maximum over -40°C to +85°C
	±20ppm Maximum over -40°C to +85°C
Supply Voltage	3.3Vdc ±5%
Input Current	3mA Maximum over Nominal Frequency of 1.024MHz to 9.999999MHz
	4mA Maximum over Nominal Frequency of 10MHz to 19.999999MHz
	5mA Maximum over Nominal Frequency of 20MHz to 39.999999MHz
	6mA Maximum over Nominal Frequency of 40MHz to 50MHz
Outrot Valtage Landa High (V.)	9mA Maximum over Nominal Frequency of 50.000001MHz to 66.6666MHz
Output Voltage Logic High (Voh)	IOH = -4mA 90% of Vdd Minimum
Output Voltage Logic Low (Vol)	IOL = +4mA
Output voltage Logic Low (Vol)	10% of Vdd Maximum
Rise/Fall Time	Measured at 20% to 80% of waveform
1110077 4111 111110	5nSec Maximum over Nominal Frequency of 1.024MHz to 24MHz
	4nSec Maximum over Nominal Frequency of 24.000001MHz to 50MHz
	3nSec Maximum over Nominal Frequency of 50.000001MHz to 66.6666MHz
Duty Cycle	Measured at 50% of Waveform
-	50 ±5(%)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Logic Control / Additional Output	Tri-State (High Impedance)
Tri-State Input Voltage (Vih and Vil)	80% of Vdd Minimum or No Connect to Enable Output, 20% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	Disabled Output: High Impedance
	10μA Maximum
RMS Phase Jitter	Fj = 12kHz to 20MHz
	1pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

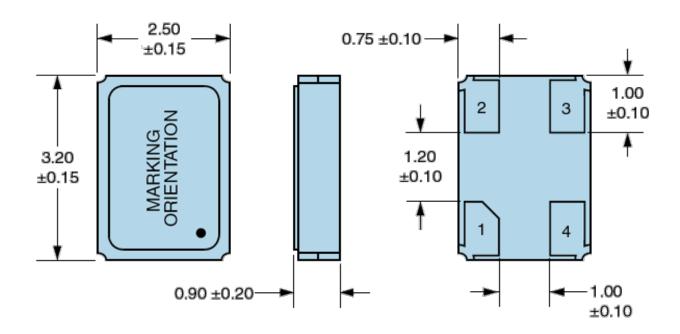


PART NUMBERING GUIDE

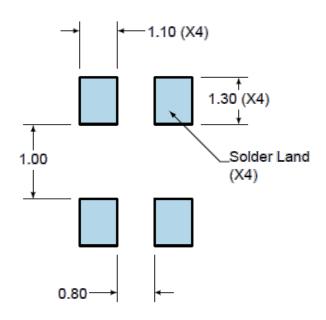




MECHANICAL DIMENSIONS



SUGGESTED SOLDER PAD LAYOUT



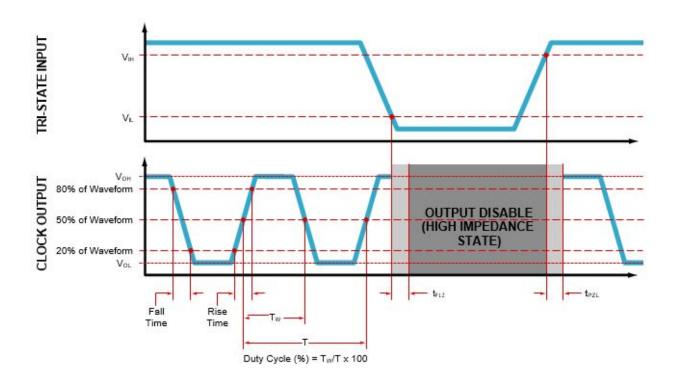
PIN	CONNECTION
1	Tri-State
2	Case/Ground
3	Output
4	Supply Voltage

All Tolerances are ±0.1

All Dimensions in Millimeters

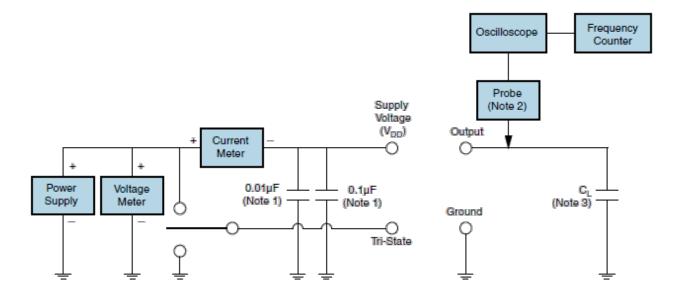


OUTPUT WAVEFORM & TIMING DIAGRAM





TEST CIRCUIT FOR CMOS OUTPUT



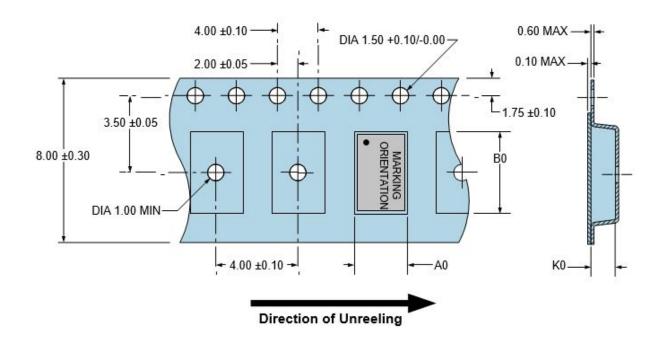
- Note 1: An external $0.1\mu F$ low frequency tantalum bypass capacitor in parallel with a $0.01\mu F$ high frequency ceramic bypass Capacitor close to the package ground and V_{DD} pin is required.
- Note 2: A low input capacitance (<12pF), 10X Attentuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) Passive probe is recommended.
- **Note 3:** Capacitance value C_L includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

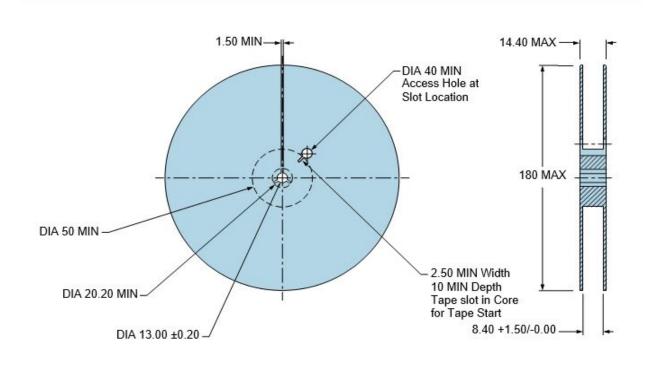


TAPE & REEL DIMENSIONS

Quantity per Reel: 1000 Units

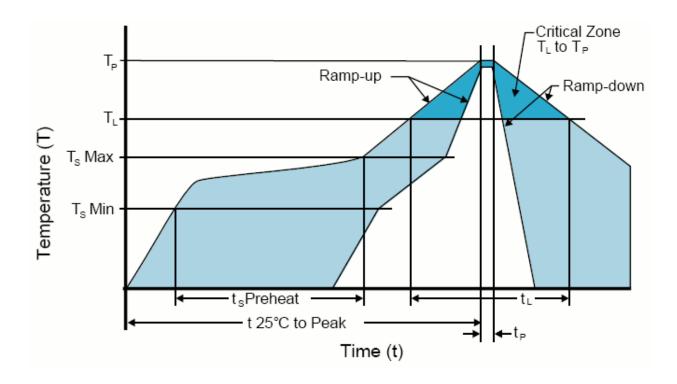
All Dimensions in Millimeters
Compliant to EIA-481







RECOMMENDED SOLDER REFLOW METHOD



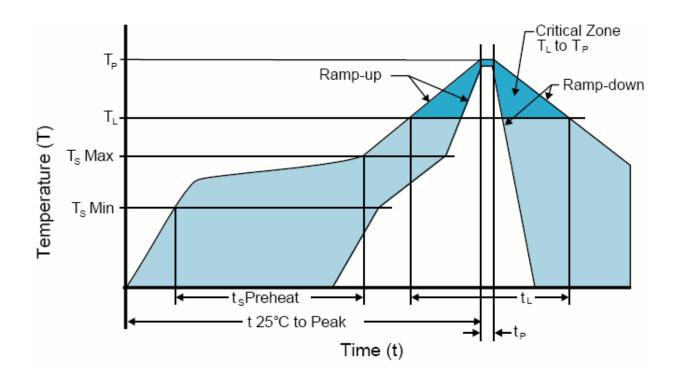
HIGH TEMPERATURE INFRARED/CONVECTION		
T _s MAX to T _L (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (T _S MIN)	150°C	
- Temperature Typical (T _s TYP)	175°C	
- reinperature waxiiiuiii(rs wax)	200°C	
- Time (t _s)	60 - 180 Seconds	
Ramp-up Rate (T _L to T _P)	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T _L)	217°C	
- Time (t _L)	60 - 150 Seconds	
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(T _P Target)	250°C +0/-5°C	
Time within 5°C of actual peak (tp)	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION		
T _s MAX to T _L (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (T _s MIN)	N/A	
- Temperature Typical (T _s TYP)	150°C	
- Temperature Maximum(T _s MAX)	N/A	
- Time (t _s)	60 - 120 Seconds	
Ramp-up Rate (T _L to T _P)	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T _L)	150°C	
- Time (t _L)	200 Seconds Maximum	
Peak Temperature (T _P)	240°C Maximum	
Target Peak Temperature (T _P Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time	
Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Standard Clock Oscillators category:

Click to view products by Abracon manufacturer:

Other Similar products are found below:

601252 F335-12 F335-25 F535L-33.333 F535L-50 ASV-20.000MHZ-LR-T ECS-2018-160-BN-TR MXO45HS-2C-66.6666MHZ
SiT8209AI-32-33E-125.000000 SIT8918AA-11-33S-50.000000G SM4420TEV-40.0M-T1K F335-24 F335-40 F535L-10 F535L-12 F535L16 F535L-24 F535L-27 F535L-48 PE7744DW-100.0M CSX-750FCC14745600T ASF1-3.686MHZ-N-K-S XO57CTECNA3M6864 ECS2100A-147.4 601251 EP16E7E2H26.000MTR SIT8918AA-11-33S-16.000000G XO3003 9120AC-2D2-33E212.500000 9102AI243N25E100.00000 8208AC-82-18E-25.00000 ASDK2-32.768KHZ-LR-T3 8008AI-72-XXE-24.545454E 8004AC-13-33E-133.33000X AS4.9152-16-SMD-TR ASFL1-48.000MHZ-LC-T SIT8920AM-31-33E-25.0000 DSC1028DI2-019.2000 9121AC-2C3-25E100.00000 9102AI233N33E100.00000X 9102AI-233N25E200.00000 9102AI-232H25S125.00000 9102AI-133N25E200.00000 9102AC-283N25E200.00000
9001AC-33-33E1-30.000 XLH536125.000JS4I 3921AI-2CF-33NZ125.000000 5730-1SF PXA000010 SIT1602BC-83-33E-10.0000000Y